ACCU-F®/ACCU-P®
THIN FILM
RF/MICROWAVE
CAPACITORS

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THE IDEAL CAPACITOR

The non-ideal characteristics of a real capacitor can be ignored at low frequencies. Physical size imparts inductance to the capacitor and dielectric and metal electrodes result in resistive losses, but these often are of negligible effect on the circuit. At the very high frequencies of radio communication (>100MHz) and satellite systems (>1GHz), these effects are never negligible. Recognizing that a real capacitor will exhibit inductive and resistive impedances in addition to capacitance, the ideal capacitor for these high frequencies is an ultra low loss component which can be fully characterized in all parameters with total repeatability from unit to unit.

Until recently, most high frequency/microwave capacitors were based on fired-ceramic (porcelain) technology. Layers of ceramic dielectric material and metal alloy electrode paste are interleaved and then sintered in a high temperature oven. This technology exhibits component variability in dielectric quality (losses, dielectric constant and insulation resistance), variability in electrode conductivity and variability in physical size (affecting inductance). An alternate thin film technology has been developed which virtually eliminates these variances. It is this technology which has been fully incorporated into ACCU-F® and ACCU-P® to provide high frequency capacitors exhibiting truly ideal characteristics.

The main features of ACCU-F® and ACCU-P® may be summarized as follows:

- ★ High purity of electrodes for very low and repeatable ESR.
- ★ Highly pure, low-K dielectric for high breakdown field, high insulation resistance and low losses to frequencies above 40GHz.
- ★ Very tight dimensional control for uniform inductance, unit to unit.
- ★ Very tight capacitance tolerances for high frequency signal applications.

This accuracy sets apart these thin film capacitors from ceramic capacitors so that the term ACCU has been employed as the designation for this series of devices, an abbreviation for “accurate.”

THIN-FILM TECHNOLOGY

Thin-film technology is commonly used in producing semiconductor devices. In the last two decades, this technology has developed tremendously, both in performance and in process control. Today’s techniques enable line definitions of below 1µm, and the controlling of thickness of layers at 100Å (10^{-2}µm). Applying this technology to the manufacture of capacitors has enabled the development of components where both electrical and physical properties can be tightly controlled.

The thin-film production facilities at AVX consist of:

- — Class 1000 clean rooms, with working areas under laminar-flow hoods of class 100, (below 100 particles per cubic foot larger than 0.5µm).
- — High vacuum metal deposition systems for high-purity electrode construction.
- — Photolithography equipment for line definition down to 2.5µm accuracy.
- — Low pressure CVD and plasma-enhanced CVD for various dielectric depositions (CVD=Chemical Vapor Deposition).
- — High accuracy, microprocessor-controlled dicing saws for die separation.
- — High speed, high accuracy sorting to ensure strict tolerance adherence.

ACCU-F® TECHNOLOGY

The use of very low-loss dielectric materials, silicon dioxide and silicon oxynitride in conjunction with highly conductive electrode metals results in low ESR and high Q. These high-frequency characteristics change at a slower rate with increasing frequency than for ceramic microwave capacitors.

Because of the thin-film technology, the above-mentioned frequency characteristics are obtained without significant compromise of properties required for surface mounting.

The main **ACCU-F®** properties are:

— Internationally agreed sizes and any custom-required sizes (subject to tooling time and charge), all with excellent dimensional control.
— Small size chip capacitors (0603) are available.
— Tight capacitance tolerances.
— Low ESR at VHF, UHF and microwave frequencies.
— High stability with respect to time, temperature, frequency and voltage variation.
— Nickel/solder-coated terminations to provide excellent solderability and leach resistance.

ACCU-F® FEATURES

ACCU-F® meets the fast-growing demand for low-loss (high-Q) capacitors for use in surface mount technology especially for the mobile communications market, such as cellular radio of 450 and 900 MHz, UHF walkie-talkies, UHF cordless telephones to 2.3 GHz, low noise blocks at 11-12.5 GHz and for other VHF, UHF and microwave applications.

ACCU-F® is currently unique in its ability to offer very low capacitance values (.1pF) and very tight capacitance tolerances (±.05pF). Typically **ACCU-F®** will be used in small signal applications in VCO's, matching networks, filters, etc.

Inspection test and quality control procedures in accordance with ISO 9001, CECC, IECQ and USA MIL Standards yield products of the highest quality.

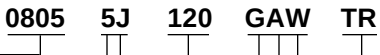
APPLICATIONS:

CELLULAR COMMUNICATIONS
CT2/PCN (CORDLESS TELEPHONE/PERSONAL COMM. NETWORKS)
SATELLITE TV
CABLE TV
GPS (GLOBAL POSITIONING SYSTEMS)
VEHICLE LOCATION SYSTEMS
VEHICLE ALARM SYSTEMS
PAGING
MILITARY COMMUNICATIONS
RADAR SYSTEMS
VIDEO SWITCHING
TEST & MEASUREMENTS
FILTERS
VCO's
MATCHING NETWORKS

APPROVALS:

ISO 9001

PART NUMBER CODES



Size: See table for standard sizes

Voltage:
1 = 100V
5 = 50V
3 = 25V

Temperature Coefficient:
(1) J = 0±30ppm/°C (-55°C to +125°C)
(1) K = 0±60ppm/°C (-55°C to +125°C)

Capacitance:
Capacitance expressed in pF.
2 significant digits + number of zeros.
For values <10pF, letter R denotes decimal point.
eg. 68pF = 680
8.2pF = 8R2

Tolerance:

for C≤5.6pF
A = ±0.05pF
B = ±0.1pF
C = ±0.25pF

for 5.6pF<C<10pF
B = ±0.1pF
C = ±0.25pF
D = ±0.5pF

for C≥10pF
F = ±1%
G = ±2%
J = ±5%

Specification Code: A = ACCU-F® technology

Termination Code: W = Nickel/solder coated (Sn 63, Pb 37)

Packaging Code: TR = Tape and reel

(1) TC's shown are per EIA/IEC Specifications.

TEMP. COEFFICIENT CODE "J" 0±30ppm/°C (-55°C to +125°C)(2)

Size						
Size Code	0603			0805		
Voltage	100	50	25	100	50	25
Cap in pF(1) — Cap code						
0.1 — 0R1 0.2 — 0R2 0.3 — 0R3 0.4 — 0R4 0.5 — 0R5 0.6 — 0R6 0.7 — 0R7 0.8 — 0R8 0.9 — 0R9						
1.0 — 1R0 1.2 — 1R2 1.5 — 1R5						
1.8 — 1R8 2.2 — 2R2 2.7 — 2R7						
3.3 — 3R3 3.9 — 3R9 4.7 — 4R7						
5.6 — 5R6 6.8 — 6R8 8.2 — 8R2						
10 — 100 12 — 120 15 — 150						
18 — 180 22 — 220 27 — 270						
33 — 330 39 — 390 47 — 470						
56 — 560 68 — 680 82 — 820						
100 — 101 120 — 121 150 — 151						

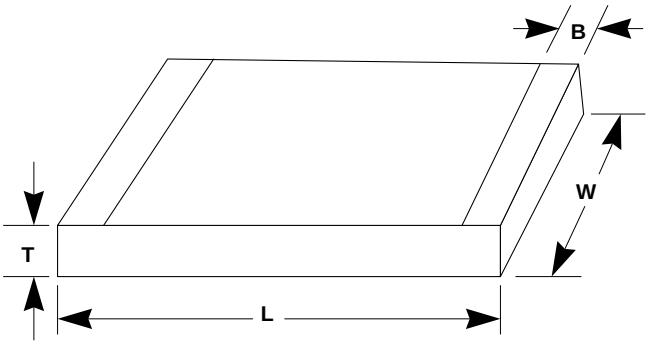
(1) For capacitance values higher than listed in table, please consult factory.
(2) TC shown is per EIA/IEC Specifications.

TEMP. COEFFICIENT CODE "K" 0±60ppm/°C (-55°C to +125°)(2)

Size						
Size Code	0603			0805		
Voltage	100	50	25	100	50	25
Capin pF(1) Cap code						
0.1 — 0R1 0.2 — 0R2 0.3 — 0R3 0.4 — 0R4 0.5 — 0R5 0.6 — 0R6 0.7 — 0R7 0.8 — 0R8 0.9 — 0R9						
1.0 — 1R0 1.2 — 1R2 1.5 — 1R5						
1.8 — 1R8 2.2 — 2R2 2.7 — 2R7						
3.3 — 3R3 3.9 — 3R9 4.7 — 4R7						
5.6 — 5R6 6.8 — 6R8 8.2 — 8R2						
10 — 100 12 — 120 15 — 150						
18 — 180 22 — 220 27 — 270						
33 — 330 39 — 390 47 — 470						
56 — 560 68 — 680 82 — 820						
100 — 101 120 — 121 150 — 151						

(1) For capacitance values higher than listed in table, please consult factory.

(2) TC shown is per EIA/IEC Specifications.



Standard sizes - mm (inches) *

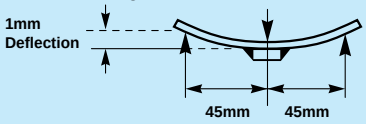
	0603	0805
L	1.6±0.1 (0.063±0.004)	2.01±0.1 (0.079±0.004)
W	0.81±0.1 (0.032±0.004)	1.27±0.1 (0.050±0.004)
T	0.63±0.1 (0.025±0.004)	0.93±0.2 (0.036±0.008)
B	0.30±0.1 (0.012±0.004)	0.30±0.1 (0.012±0.004)

ELECTRICAL SPECIFICATIONS

Operating and Storage Temperature Range	-55°C to +125°C
Temperature Coefficients (1)	0 ± 30ppm/°C dielectric code "J" 0 ± 60ppm/°C dielectric code "K"
Capacitance Measurement	1 MHz, 1 Vrms
Insulation Resistance (IR)	$\geq 10^{11}$ ohms
Proof Voltage	2.5 U_R for 5 secs
Aging Characteristic	Zero
Dielectric Absorption	0.01%

(1) TC's shown are per EIA/IEC

MECHANICAL CHARACTERISTICS

TEST	CONDITIONS	REQUIREMENT
Solderability **MIL-STD-202F Method 208A**	Components completely immersed in a solder bath at 235°C for 2 secs.	Terminations to be well tinned, minimum 95% coverage
Leach Resistance **MIL-STD-202F Method 210A**	Components completely immersed in a solder bath at 260±5°C for 60 secs.	Dissolution of termination faces ≤15% of area Dissolution of termination edges ≤25% of length
Adhesion **MIL-STD-202F Method 211A**	A force of 5N applied for 10 secs.	No visible damage
Termination Bond Strength **IEC-680-2-21 Amend. 2**	Tested as shown in diagram 	No visible damage Δ C/C ≤ 2% for C≥5pF Δ C ≤ 0.25pF for C<5pF
Robustness of Termination **IEC-680-2-21 Amend. 2**	A force of 5N applied for 10 secs.	No visible damage
Storage	12 months minimum with components stored in "as received" packaging.	Good solderability

ACCU-F® is based on well established thin-film technology and materials.

- **Inline Process Control:** This program forms an integral part of the production cycle and acts as a feedback system to regulate and control production processes. The test procedures, which are integrated into the production process, were developed after long research work and are based on the highly developed semiconductor industry test procedures and equipment. These measures help AVX to produce a consistent and high yield line of products.

- **Final Quality Inspection:** Finished parts are tested for standard electrical parameters and visual/mechanical characteristics. Each production lot is 100% evaluated for: capacitance and proof voltage at 2.5 U_R. In addition, production is periodically evaluated for:

  Average capacitance with histogram printout for capacitance distribution.
  IR and Breakdown Voltage distribution.
  Temperature Coefficient.
  Solderability testing.
  Dimensional, mechanical and temperature stability.

- **Quality Assurance:** The reliability of these thin film chip capacitors has been studied intensively for several years. Various measures have been taken to obtain the high reliability required today by the industry. Quality assurance policy is based on well established international industry standards. The reliability of the capacitors is determined by accelerated testing under the following conditions:

Endurance Test	125°C, $2U_R$, 1000 hours
Accelerated Damp Heat Steady State Testing	85°C, 85% RH, U_R, 1000 hours.

ACCU-P® TECHNOLOGY

As in the **ACCU-F®** series the use of very low-loss dielectric materials (silicon dioxide and silicon oxynitride) in conjunction with highly conductive electrode metals results in low ESR and high Q. At high frequency these characteristics change at a slower rate with increasing frequency than conventional ceramic microwave capacitors. Using thin-film technology, the above-mentioned frequency characteristics are obtained without significant compromise of properties required for surface mounting. The use of high thermal conductivity materials results in excellent RF power handling capabilities.

The main **ACCU-P®** properties are:

— Enhanced RF power handling capability.
— Improved mechanical characteristics.
— Internationally agreed sizes with excellent dimensional control.
— Small size chip capacitors are available.
— Tight capacitance tolerances.
— Low ESR at UHF, VHF, and Microwave frequencies.
— High-stability with respect to time, temperature, frequency and voltage variation.
— High temperature nickel/solder-coated terminations as standard to provide excellent solderability and leach resistance.

ACCU-P® FEATURES

★ The **ACCU-P®** has the same unique features as the **ACCU-F®** capacitor such as low ESR, high Q, availability of very low capacitance values and very tight capacitance tolerances.
★ The RF power handling capability of the **ACCU-P®** allows for its usage in both small signal and RF power applications.
★ Inspection, test and quality control procedures in accordance with ISO 9001, CECC, IECQ and USA MIL Standards guarantee product of the highest quality.

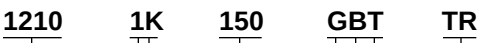
APPLICATIONS:

CELLULAR COMMUNICATIONS
CT2/PCN (CORDLESS TELEPHONE/PERSONAL COMM. NETWORKS)
SATELLITE TV
CABLE TV
GPS (GLOBAL POSITIONING SYSTEMS)
VEHICLE LOCATION SYSTEMS
VEHICLE ALARM SYSTEMS
PAGING
MILITARY COMMUNICATIONS
RADAR SYSTEMS
VIDEO SWITCHING
TEST AND MEASUREMENTS
FILTERS
VCO'S
MATCHING NETWORKS
RF AMPLIFIERS

APPROVALS:

ISO 9001

PART NUMBER CODES



Size: See table for standard sizes

Voltage:
1 = 100V
5 = 50V
3 = 25V

Temperature Coefficient:
(1) J = 0±30ppm/°C (-55°C to +125°C)
(1) K = 0±60ppm/°C (-55°C to +125°C)

Capacitance: Capacitance expressed in pF.
2 significant digits + number of zeros.
For values <10pF, letter R denotes decimal point.
eg. 24pF = 240
8.2pF = 8R2

Tolerance:

for C≤5.6pF
A = ± 0.05pF
B = ± 0.1pF
C = ± 0.25pF

for 5.6pF < C < 10pF
B = ± 0.1pF
C = ± 0.25pF
D = ± 0.5pF

for C ≥10pF
F = ± 1%
G = ± 2%
J = ± 5%

Specification Code: B = ACCU-P® technology

Termination Code: T = Nickel/High temperature solder coated (Sn 96, Ag 4)

Packaging Code: TR = Tape and reel

(1) TC's shown are per EIA/IEC Specifications.

TEMP. COEFFICIENT CODE "J" 0±30ppm/°C (-55°C to +125°C)(2)

Size							
Size Code	0603		0805			1210	
Voltage	50	25	100	50	25	100	50
Cap in pF(1) / Cap code							
0.1 — 0R1 0.2 — 0R2 0.3 — 0R3 0.4 — 0R4 0.5 — 0R5 0.6 — 0R6 0.7 — 0R7 0.8 — 0R8 0.9 — 0R9							
1.0 — 1R0 1.2 — 1R2 1.5 — 1R5							
1.8 — 1R8 2.2 — 2R2 2.7 — 2R7							
3.3 — 3R3 3.9 — 3R9 4.7 — 4R7							
5.6 — 5R6 6.8 — 6R8 7.5 — 7R5							
8.2 — 8R2 10 — 100 12 — 120							
15 — 150 18 — 180 22 — 220							
24 — 240 27 — 270 33 — 330							

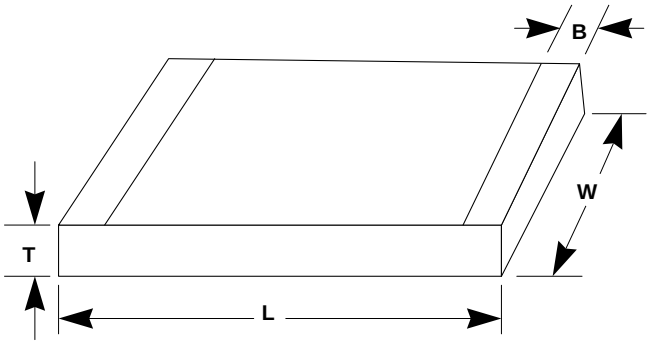
(1) For capacitance values higher than listed in table, please consult factory.

(2) TC shown is per EIA/IEC specifications.

TEMP. COEFFICIENT CODE "K" 0±60ppm/°C (-55°C to +125°C)(2)

Size					
Size Code	0805			1210	
Voltage	100	50	25	100	50(3)
Cap in pF(1) — Cap code					
0.1 — 0R1 0.2 — 0R2 0.3 — 0R3 0.4 — 0R4 0.5 — 0R5 0.6 — 0R6 0.7 — 0R7 0.8 — 0R8 0.9 — 0R9					
1.0 — 1R0 1.2 — 1R2 1.5 — 1R5					
1.8 — 1R8 2.2 — 2R2 2.7 — 2R7					
3.3 — 3R3 3.9 — 3R9 4.7 — 4R7					
5.6 — 5R6 6.8 — 6R8 7.5 — 7R5					
8.2 — 8R2 10 — 100 12 — 120					
15 — 150 18 — 180 22 — 220					
24 — 240 27 — 270 33 — 330 39 — 390					
47 — 470 56 — 560 68 — 680 82 — 820					
100 — 101					

(1) For capacitance values higher than listed in table, please consult factory.
(2) TC shown is per EIA/IEC specifications.
(3) For 50 volt range please consult factory.



Standard sizes - mm (inches)

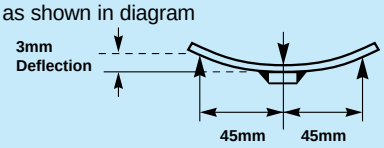
	0603	0805	1210
L	1.60±0.1 (0.063±0.004)	2.01±0.1 (0.079±0.004)	3.02±0.1 (0.119±0.004)
W	0.81±0.1 (0.032±0.004)	1.27±0.1 (0.050±0.004)	2.5±0.1 (0.100±0.004)
T	0.63±0.1 (0.025±0.004)	0.93±0.2 (0.036±0.008)	0.93±0.2 (0.036±0.008)
B	0.35±0.15 (0.014±0.006)	0.30±0.1 (0.012±0.004)	0.43±0.1 (0.017±0.004)

ELECTRICAL SPECIFICATIONS

Operating and Storage Temperature Range	-55°C to +125°C
Temperature Coefficient (1)	0 ± 30ppm/°C dielectric code "J" 0 ± 60ppm/°C dielectric code "K"
Capacitance Measurement	1 MHz, 1 Vrms
Insulation Resistance (IR)	$\geq 10^{11}$ ohms
Proof Voltage	2.5% U_R for 5 secs.
Aging Characteristic	Zero
Dielectric Absorption	0.01%

(1) TC's shown are per EIA/IEC

MECHANICAL CHARACTERISTICS

TEST	CONDITIONS	REQUIREMENT
Solderability **MIL-STD-202F Method 208A**	Components completely immersed in a solder bath at 235°C for 2 secs.	Terminations to be well tinned, minimum 95% coverage
Leach Resistance **MIL-STD-202F Method 210A**	Components completely immersed in a solder bath at 260±5°C for 60 secs.	Dissolution of termination faces ≤15% of area Dissolution of termination edges ≤25% of length
Adhesion **MIL-STD-202F Method 211A**	A force of 5N applied for 10 secs.	No visible damage
Termination Bond Strength **IEC-680-2-21 Amend. 2**	Tested as shown in diagram 	No visible damage Δ C/C ≤ 2% for C≥5pF Δ C ≤ 0.25pF for C<5pF
Robustness of Termination **IEC-680-2-21 Amend. 2**	A force of 5N applied for 10 secs	No visible damage
High Frequency Vibration **MIL-STD-202F Method 204D**	55Hz to 2000Hz, 20G	No visible damage
Storage	12 months minimum with components stored in "as received" packaging	Good solderability

ENVIRONMENTAL CHARACTERISTICS

TEST	CONDITIONS	REQUIREMENT
Life **MIL-STD-202F Method 108A**	125°C, 2U_R, 1000 hours	No visible damage Δ C/C ≤ 2% for C≥5pF Δ C ≤ 0.25pF for C<5pF
Accelerated Damp Heat Steady State **MIL-STD-202F Method 103B**	85°C, 85% RH, U_R, 1000 hours	No visible damage Δ C/C ≤ 2% for C≥5pF Δ C ≤ 0.25pF for C<5pF
Thermal Shock **MIL-STD-202F Method 107E**	-55°C to +125°C, 15 cycles	No visible damage Δ C/C ≤ 2% for C≥5pF Δ C ≤ 0.25pF for C<5pF
Resistance to Solder Heat **MIL-STD-202F Method 210A**	260°C ± 5°C for 10 secs	C remains within initial limits

ACCU-P® is based on well established thin-film technology and materials.

- **Inline Process Control:** This program forms an integral part of the production cycle and acts as a feedback system to regulate and control production processes. The test procedures, which are integrated into the production process, were developed after long research work and are based on the highly developed semiconductor industry test procedures and equipment. These measures help AVX to produce a consistent and high yield line of products.

- **Final Quality Inspection:** Finished parts are tested for standard electrical parameters and visual/mechanical characteristics. Each production lot is 100% evaluated for: capacitance and proof voltage at 2.5 U_R. In addition, production is periodically evaluated for:

  Average capacitance with histogram printout for capacitance distribution.
  IR and Breakdown Voltage distribution.
  Temperature Coefficient.
  Solderability testing.
  Dimensional, mechanical and temperature stability.

- **Quality Assurance:** The reliability of these thin film chip capacitors has been studied intensively for several years. Various measures have been taken to obtain the high reliability required today by the industry. Quality assurance policy is based on well established international industry standards. The reliability of the capacitors is determined by accelerated testing under the following conditions:

Endurance Test	125°C, $2U_R$, 1000 hours
Accelerated Damp Heat Steady State Testing	85°C, 85% RH, U_R, 1000 hours.

RF POWER APPLICATIONS

In RF power applications, capacitor losses generate heat. Two factors of particular importance to designers are:

— Minimizing the generation of heat.

— Dissipating heat as efficiently as possible.

CAPACITOR HEATING

★ The major source of heat generation in a capacitor in RF power applications is a function of RF current (I) and ESR, from the relationship:

$$\text{Power dissipation} = I^2_{RMS} \times ESR$$

★ **ACCU-P®** capacitors are specially designed to minimize ESR and therefore RF heating. Values of ESR for **ACCU-P®** capacitors are significantly less than those of ceramic MLC components currently available.

HEAT DISSIPATION

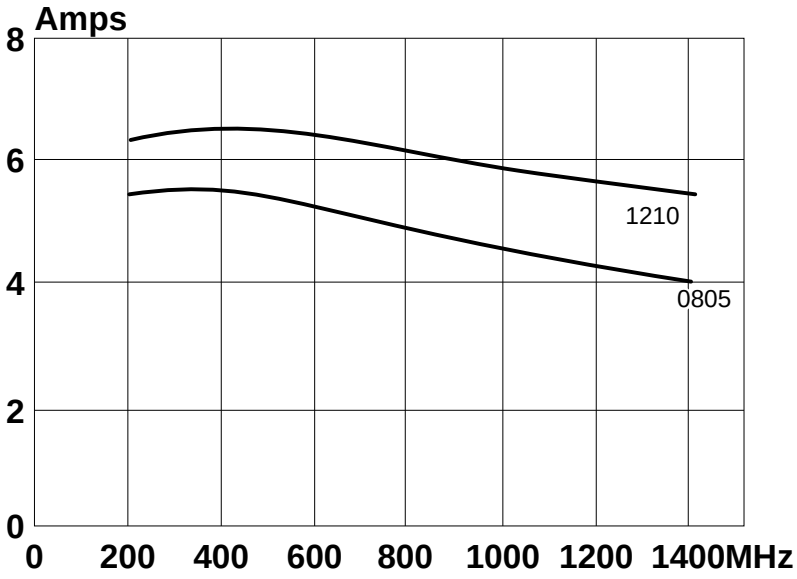
★ Heat is dissipated from a capacitor through a variety of paths, but the key factor in the removal of heat is the thermal conductivity of the capacitor material.

★ The higher the thermal conductivity of the capacitor, the more rapidly heat will be dissipated.

★ The table below illustrates the importance of thermal conductivity to the performance of **ACCU-P®** in power applications.

Product	Material	Thermal Conductivity W/mK
ACCU-P® Microwave MLC	Alumina Magnesium Titanate	18.9 6.0

Power Handling ACCU-P® 10 pF



Data used in calculating the graph:

Thermal impedance of capacitors:

0805 6.5°C/W

1210 5°C/W

Thermal impedance measured using RF generator, amplifier and strip-line transformer.

ESR of capacitors measured on Boonton 34A

THERMAL IMPEDANCE

Thermal impedance of **ACCU-P®** chips is shown below compared with the thermal impedance of Microwave MLC's.

The thermal impedance expresses the temperature difference in °C between chip center and termination caused by a power dissipation of 1 watt in the chip. It is expressed in °C/W.

Capacitor Type	Chip Size	Thermal Impedance °C/W
ACCU-P®	0805 1210	6.5 5
Microwave MLC	0505 1210	12 7.5

ADVANTAGES OF ACCU-P® IN RF POWER CIRCUITS

The optimized design of **ACCU-P®** offers the designer of RF power circuits the following advantages:

★ Reduced power losses due to the inherently low ESR of **ACCU-P®**.

★ Increased power dissipation due to the high thermal conductivity of **ACCU-P®**.

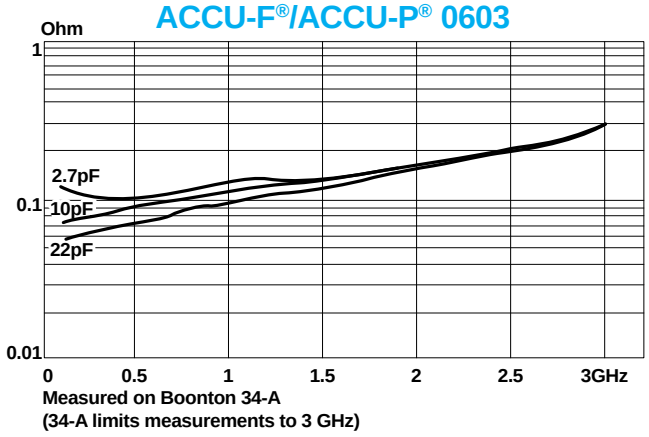
PRACTICAL APPLICATION IN RF POWER CIRCUITS

★ There is a wide variety of different experimental methods for measuring the power handling performance of a capacitor in RF power circuits. Each method has its own problems and few of them exactly reproduce the conditions present in "real" circuit applications.

★ Similarly, there is a very wide range of different circuit applications, all with their unique characteristics and operating conditions which cannot possibly be covered by such "theoretical" testing.

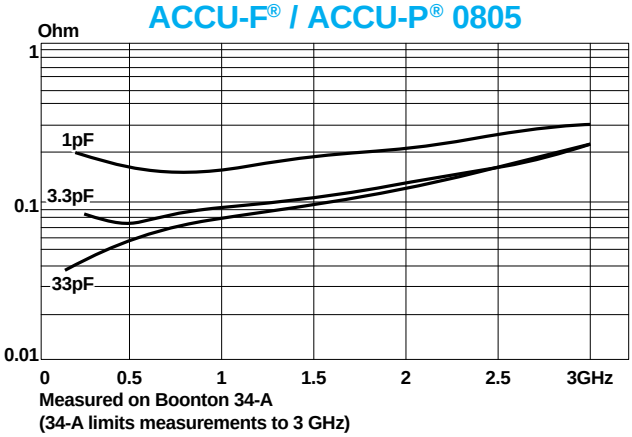
★ THE ONLY TRUE TEST OF A CAPACITOR IN ANY PARTICULAR APPLICATION IS ITS PERFORMANCE UNDER OPERATING CONDITIONS IN THE ACTUAL CIRCUIT.

ESR
ACCU-F®/ACCU-P® 0603



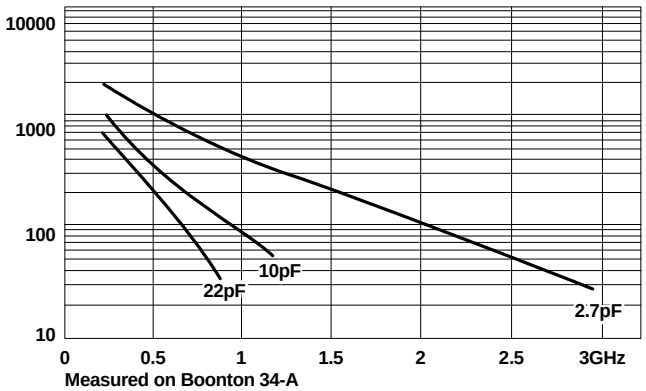
Measured on Boonton 34-A
(34-A limits measurements to 3 GHz)

ESR
ACCU-F® / ACCU-P® 0805



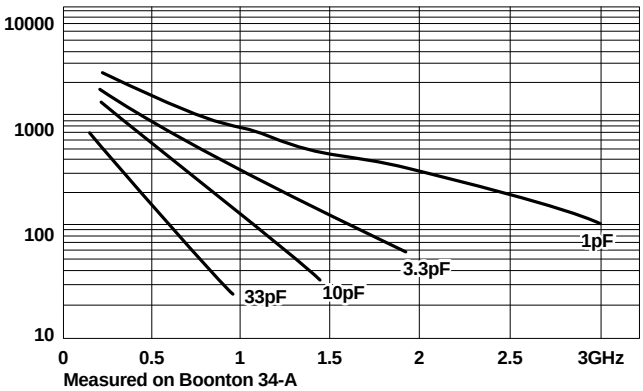
Measured on Boonton 34-A
(34-A limits measurements to 3 GHz)

Q
ACCU-F®/ACCU-P® 0603



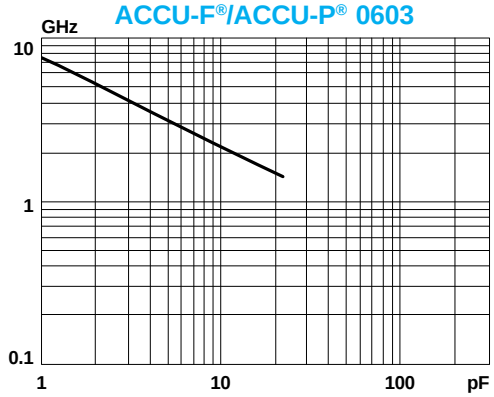
Measured on Boonton 34-A
(34-A limits measurements to 3GHz)

Q
ACCU-F® / ACCU-P® 0805



Measured on Boonton 34-A
(34-A limits measurements to 3GHz)

Self Resonant Frequency
ACCU-F®/ACCU-P® 0603

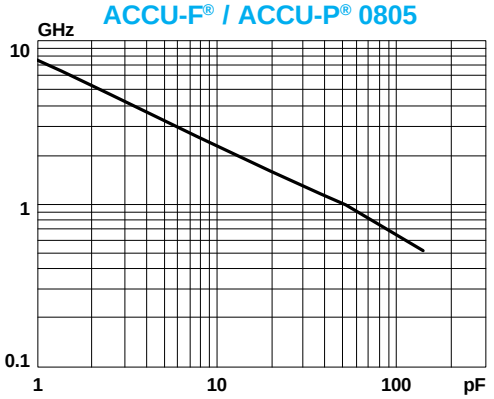


L (self inductance) ~ 0.78 nH

NOTE
L and SRF are obtained from the measured increase in effective capacitance as the frequency is increased

Measured on the Boonton 34-A

Self Resonant Frequency
ACCU-F® / ACCU-P® 0805

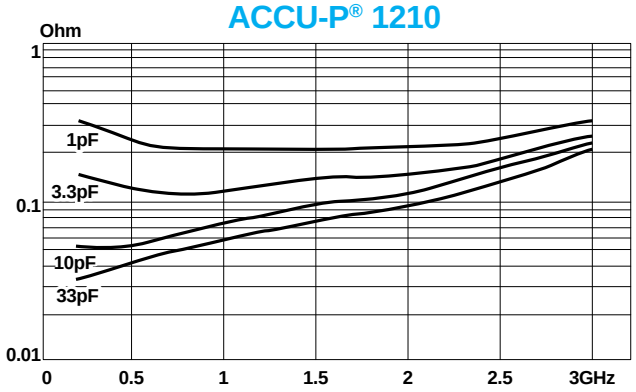


L (self inductance) ~ 0.82 nH

NOTE
L and SRF are obtained from the measured increase in effective capacitance as the frequency is increased

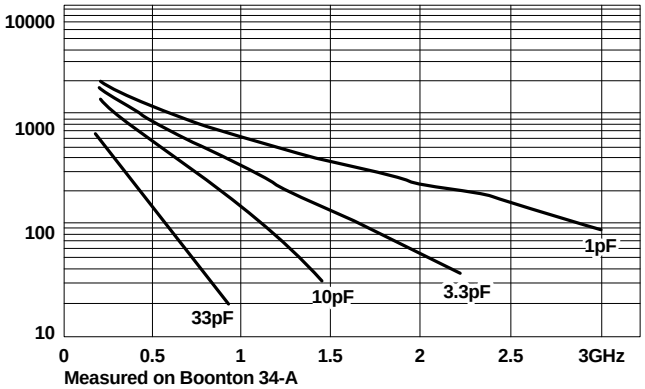
Measured on the Boonton 34-A

ESR
ACCU-P® 1210



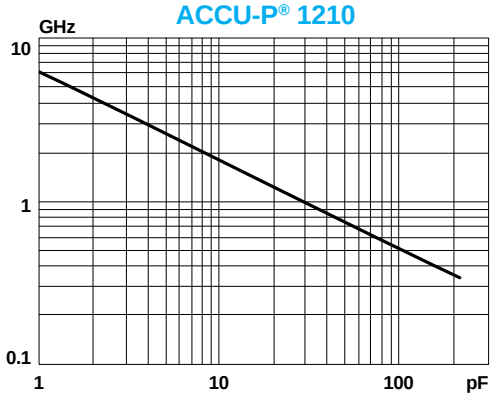
Measured on Boonton 34-A
(34-A limits measurements to 3 GHz)

Q
ACCU-P® 1210



Measured on Boonton 34-A
(34-A limits measurements to 3GHz)

Self Resonant Frequency
ACCU-P® 1210

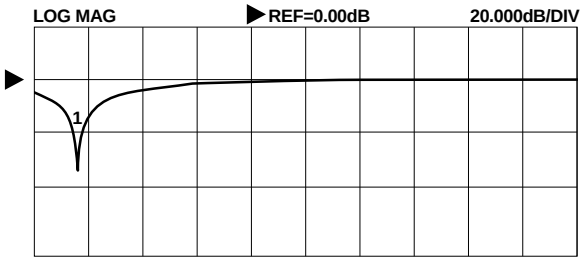


L (self inductance) ~ 1.02 nH

NOTE
L and SRF are obtained from the measured increase in effective capacitance as the frequency is increased

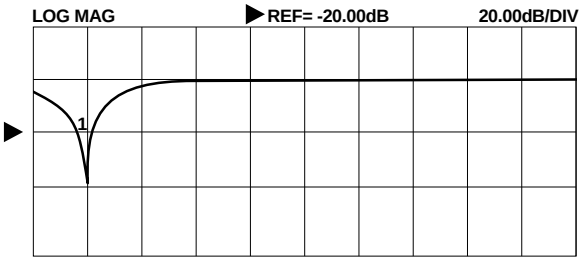
Measured on the Boonton 34-A

S21 FORWARD TRANSMISSION
LOG MAG REF=0.00dB 20.000dB/DIV



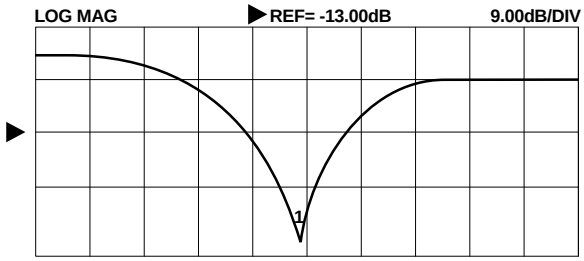
0603 1pF MARKER 1: SRF = 6.88 GHz

S21 FORWARD TRANSMISSION
LOG MAG REF= -20.00dB 20.00dB/DIV



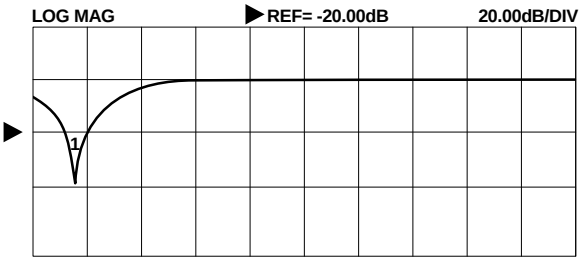
0603 2.7pF MARKER 1: SRF = 3.764 GHz

S21 FORWARD TRANSMISSION
LOG MAG REF= -13.00dB 9.00dB/DIV



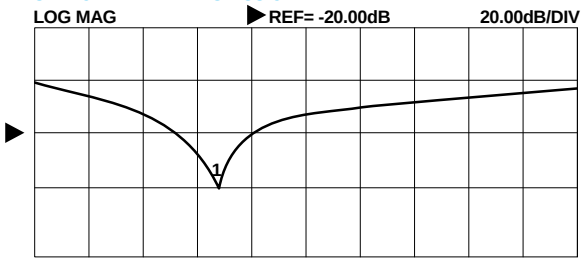
0805 0.6pF MARKER 1: SRF = 10.748 GHz

S21 FORWARD TRANSMISSION
LOG MAG REF= -20.00dB 20.00dB/DIV



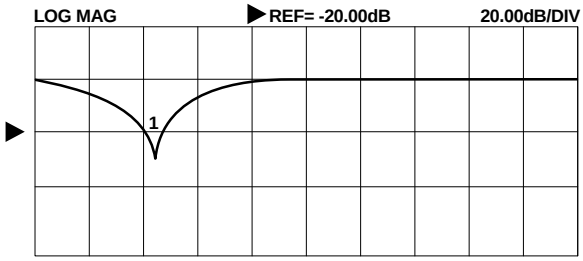
0805 3.3pF MARKER 1: SRF = 3.548 GHz

S21 FORWARD TRANSMISSION
LOG MAG REF= -20.00dB 20.00dB/DIV



1210 10pF MARKER 1: SRF = 2.0390 GHz

S21 FORWARD TRANSMISSION
LOG MAG REF= -20.00dB 20.00dB/DIV



1210 1.2pF MARKER 1: SRF = 5.888 GHz

Measured using WILTRON 360 VECTOR ANALYZER with WILTRON 3680K UNIVERSAL TEST FIXTURE

ACCU-F® AND ACCU-P® APPLICATION NOTES

General

ACCU-F® and ACCU-P® SMD capacitors are designed for soldering to printed circuit boards or other substrates. The construction of the components is such that they will withstand the time/temperature profiles used in both wave and reflow soldering methods.

Handling

SMD capacitors should be handled with care to avoid damage or contamination from perspiration and skin oils. The use of plastic tipped tweezers or vacuum pick-ups is strongly recommended for individual components. Bulk handling should ensure that abrasion and mechanical shock are minimized. For automatic equipment, taped and reeled product gives the ideal medium for direct presentation to the placement machine.

Circuit Board Type

The circuit board types which may be used with ACCU-F® and ACCU-P® are as follows:

ACCU-F®: All flexible types of circuit boards (eg. FR-4, G-10).
ACCU-P®: All flexible types of circuit boards (eg. FR-4, G-10) and also alumina.

For other circuit board materials, please consult factory.

Component Pad Design

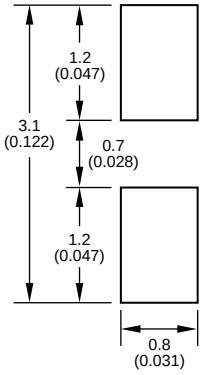
Component pads must be designed to achieve good joints and minimize component movement during reflow soldering. Pad designs are given below for both wave and reflow soldering.

The basis of these designs is:

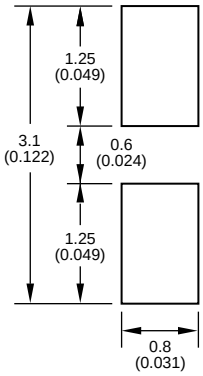
a. Pad width equal to component width. It is permissible to decrease this to as low as 85% of component width but it is not advisable to go below this.
b. Pad overlap 0.5mm beneath large components. Pad overlap about 0.3mm beneath small components.
c. Pad extension of 0.5mm for reflow of large components and pad extension about 0.3mm for reflow of small components. Pad extension about 1.0mm for wave soldering.

Wave Soldering

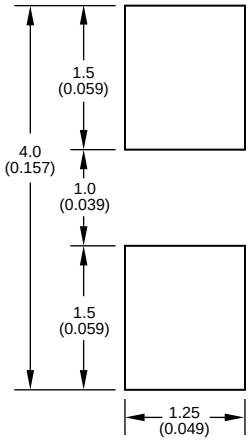
Dimensions in mm(inches).



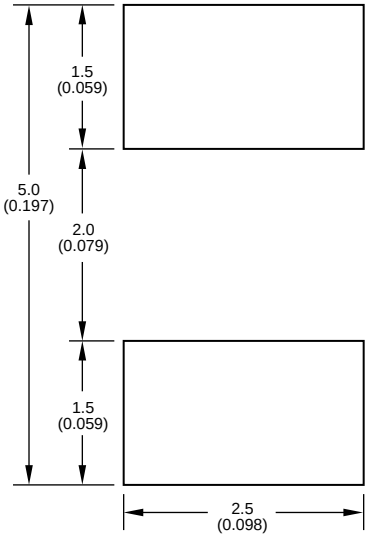
0603
ACCU-F®



0603
ACCU-P®



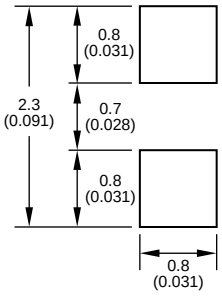
0805
ACCU-F®
ACCU-P®



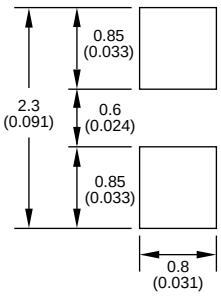
1210
ACCU-P®

Reflow Soldering

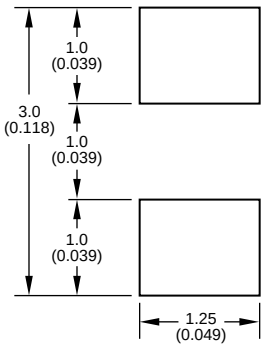
Dimensions in mm(inches).



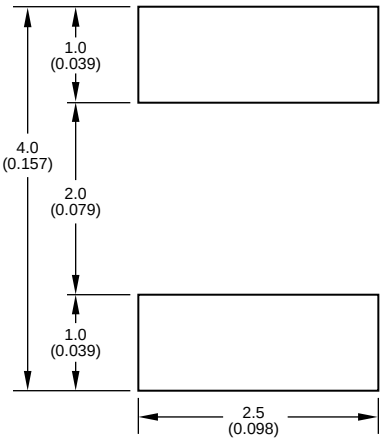
0603
ACCU-F®



0603
ACCU-P®



0805
ACCU-F®
ACCU-P®



1210
ACCU-P®

Preheat & Soldering

The rate of preheat in production should not exceed 4°C/second and a recommended maximum is about 2°C/second. Temperature differential from preheat to soldering should not exceed 100°C.
For further specific application or process advice please consult AVX.

Cooling

After soldering, the assembly should preferably be allowed to cool naturally. In the event of assisted cooling, similar conditions to those recommended for preheating should be used.

Hand Soldering & Rework

Hand soldering is permissible. Preheat of the PCB to 150°C is required. The most preferable technique is to use hot air soldering tools. Where a soldering iron is used, a temperature controlled model not exceeding 30 watts should be used and set to not more than 150°C.

Cleaning Recommendations

Care should be taken to ensure that the devices are thoroughly cleaned of flux residues, especially the space beneath the device. Such residues may otherwise become conductive and effectively offer a lossy bypass to the device. Various recommended cleaning conditions (which must be optimized for the flux system being used) are as follows:

Cleaning liquids	i-propanol, ethanol, acetylacetone, water and other standard PCB cleaning liquids.
Ultrasonic conditions	power–20w/liter max. frequency–20kHz to 45kHz.
Temperature	80°C maximum (if not otherwise limited by chosen solvent system).
Time	5 minutes max.

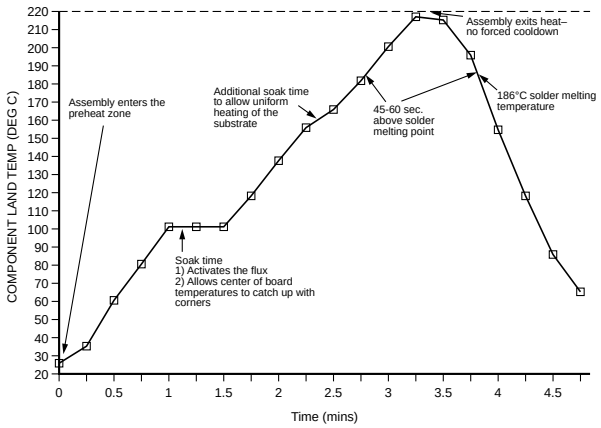
Storage Conditions

Recommended storage conditions for ACCU-F® and ACCU-P® prior to use are as follows:

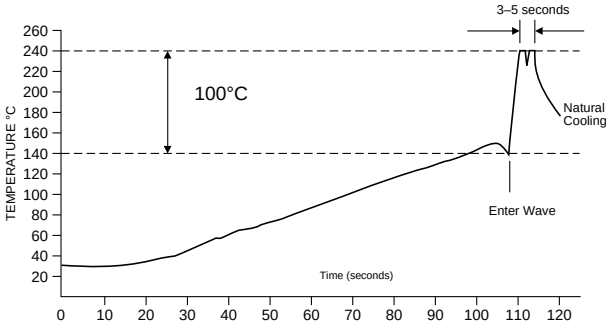
Temperature	15°C to 35°C
Humidity	≤65%
Air Pressure	860mbar to 1060mbar

Recommended Soldering Profiles

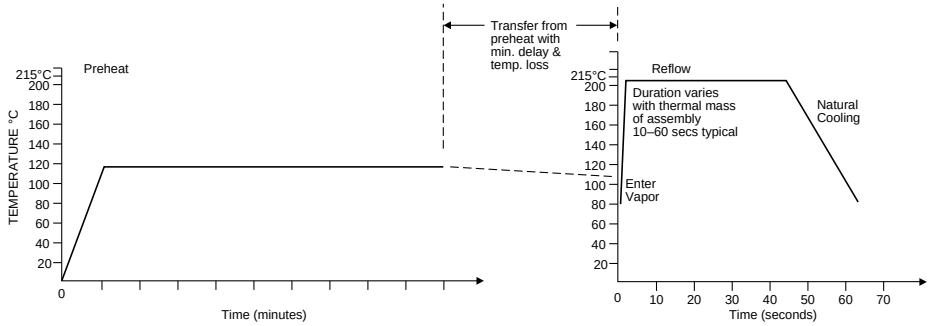
IR Reflow



Wave Soldering



Vapor Phase



Design Kit Type 100

Order Number: ACCU-F®0805KIT01

Volts	Capacitors Value pF	Tolerance
100	0.5	B
	0.6	B
	0.7	B
	0.8	B
	0.9	B
	1.0	B
	1.2	B
	1.5	B
	1.8	B
	2.0	B
	2.2	B
	2.4	B
	2.7	B
	3.0	B
	3.3	B
	3.9	B
	4.7	B
	5.6	B
	6.8	B
	8.2	B
	10	G
	12	G
	15	G
50	18	G
	22	G
	27	G
	33	G
25	39	G
	47	G
	56	G

300 CAPACITORS, 10 EACH OF 30 VALUES

TOLERANCE B = ± 0.1pF
G = ± 2%

Design Kit Type 400

Order Number: ACCU-F®0603KIT01

Volts	Capacitors Value pF	Tolerance
100	0.1	B
	0.2	B
	0.3	B
	0.4	B
	0.5	B
	0.6	B
	0.7	B
	0.8	B
	0.9	B
	1.0	B
	1.1	B
	1.2	B
	1.5	B
	1.8	B
	2.0	B
	2.2	B
	2.4	B
	2.7	B
	3.0	B
	3.3	B
	3.9	B
	4.7	B
50	5.6	C
	6.8	C
	8.2	C
	10	G
	12	G
	15	G
25	18	G
	22	G

300 CAPACITORS, 10 EACH OF 30 VALUES

TOLERANCE B = ± 0.1pF
C = ± 0.25pF
G = ± 2%

Tuning Kit Type 700

Order Number: ACCU-P®1210KIT02

Volts	Capacitors Value pF	Tolerance
100	1.0	B
	1.5	B
	1.8	B
	2.2	B
	2.7	B
	3.3	B
	4.7	B
	5.6	B
	6.8	B
	10.0	G
	12	G
	18	G
	22	G
	27	G
	33	G

150 CAPACITORS, 10 EACH OF 15 VALUES

TOLERANCE B = ± 0.1pF
G = ± 2%

Designer Kit Type 800

Order Number: ACCU-P®0805KIT02

Volts	Capacitors Value pF	Tolerance
100	0.1	A
	0.2	A
	0.3	A
	0.4	A
	0.5	B
	0.7	B
	0.8	B
	0.9	B
	1.0	B
	1.2	B
	1.5	B
	1.8	B
	2.0	B
	2.2	B
	2.7	B
	3.3	B
	3.9	B
	4.7	B
	5.6	B
	6.8	B
	8.2	B
	10.0	G
50	12.0	G
	15.0	G
	18.0	G
	22.0	G
	27.0	J
	33.0	J
25	39.0	J
	47.0	J

300 CAPACITORS, 10 EACH OF 30 VALUES

TOLERANCE A = ± 0.05pF
B = ± 0.1pF
G = ± 2%
J = ±5%

Designer Kit Type 900

Order Number: ACCU-P®0603KIT01

Volts	Capacitors Value pF	Tolerance
50	0.1	A
	0.2	A
	0.3	A
	0.4	B
	0.5	B
	0.6	B
	0.7	B
	0.8	B
	0.9	B
	1.0	B
	1.1	B
	1.2	B
	1.5	B
	1.8	B
	2.0	B
	2.2	B
	2.4	B
	2.7	B
	3.0	B
	3.3	B
	3.9	B
	4.7	B
	5.6	B
	6.8	B
	8.2	G
	10.0	G
	12.0	G
	15.0	G
25	18.0	G
	22.0	G

600 CAPACITORS, 20 EACH OF 30 VALUES

TOLERANCE A = ± 0.05pF
B = ± 0.1pF
G = ± 2%

Automatic Insertion Packaging

Tape & Reel All tape and reel specifications are in compliance with EIA RS481 (equivalent to IEC 286 part 3).
—8mm carrier
—Reeled quantities: Reels of 3,000 or 10,000 pieces

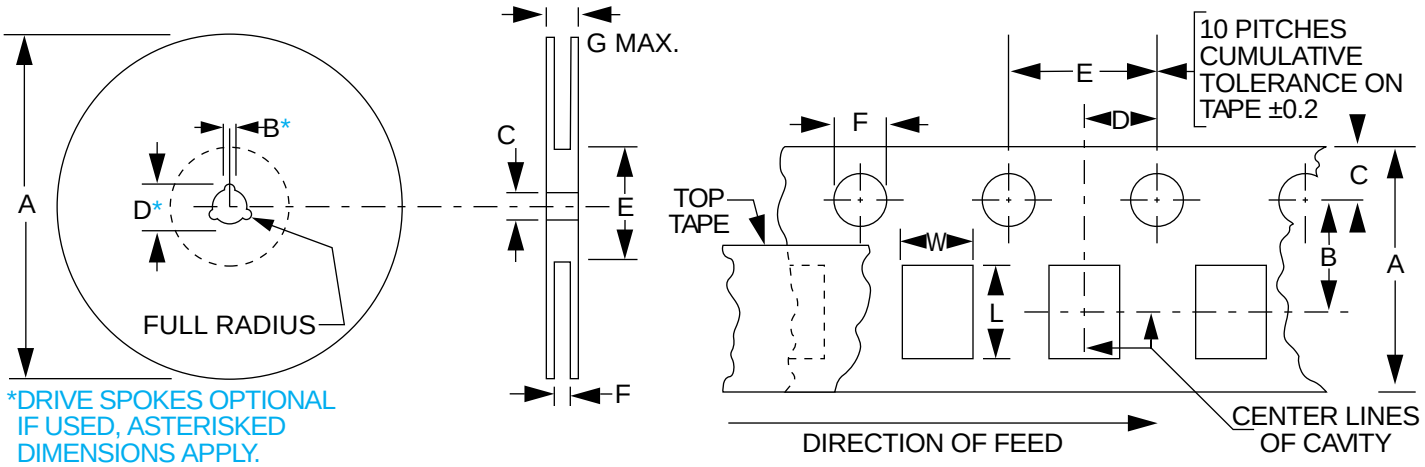
Reel Dimensions mm (inches)

(1) A	B	C	D	E	F	G
180±1.0 (7.087±0.039)	1.5 min. (0.059 min.)	13±0.2 (0.512 ± 0.008)	20.2min. (0.795 min.)	50min. (1.969 min.)	9.6±1.5 (0.370 ± 0.050)	14.4 max. (0.567 max.)
Metric dimensions will govern. Inch measurements rounded and for reference only.						

(1) 330mm (13 inch) reels are available.

Carrier Dimensions mm (inches)

A	B	C	D	E	F
8.0 ± 0.3 (0.315 ± 0.012)	3.5 ± 0.05 (0.138 ± 0.002)	1.75±0.1 (0.069 ± 0.004)	2.0 ± 0.05 (0.079 ± 0.002)	4.0 ± 0.1 (0.157 ± 0.004)	$1.5^{+0.1}_{-0.0}$ ($0.059^{+0.004}_{-0.000}$)
NOTE: The nominal dimensions of the component compartment are derived from the component size.					



NOTE: AVX reserves the right to change the information published herein without notice.

For more information regarding AVX's Accu Series of SMD Thin Film Products:

Accu-Guard® Accu-F®/Accu-P® Accu-L®

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